

| Issue | Market Index | VIP Interview | Cover Story | Trend Insights | Components & Modules | Distribution & Supply Chain | Manufacturing and Process | Specials |
|--|--------------|---------------|---|---|--------------------------------------|--|---------------------------------------|---|
| January Ad Booking Deadline: 21-Nov-2025 Ad Materials Deadline: 28-Nov-2025 | • | • | 2026 Electronics industry trends | Current State of the Consumer Electronics Market | Power IC/Modules | 2026 Electronics and distribution industry outlook | - | - |
| February Ad Booking Deadline: 22-Dec-2025 Ad Materials Deadline: 30-Dec-2025 | • | • | The diversified chain tide of global supply chains | Chip Going Global | Storage Controller | Sustainable Supply Chain | Automated Testing | - |
| March Ad Booking Deadline: 20-Jan-2026 Ad Materials Deadline: 28-Jan-2026 | • | • | Intelligent Manufacturing and Digital Supply Chain | Machine Vision | Sensor | Supply Chain Management | - | - |
| April Ad Booking Deadline: 25-Feb-2026 Ad Materials Deadline: 27-Feb-2026 | • | • | AI Phone / AI PC applications | VR/AR | -Capacitor -Resistor -Inductor | Electronics Components E-commerce | PCB manufacturing | - |
| May Ad Booking Deadline: 20-Mar-2026 Ad Materials Deadline: 30-Mar-2026 | • | • | Deep Convergence of New Energy and Intelligent Driving | AI-Defined Vehicle | Wireless Module | Supply Chain Services | - | - |
| June Ad Booking Deadline: 20-Apr-2026 Ad Materials Deadline: 30-Apr-2026 | • | • | 2025 Global / China Electronic Component Distributor Rankings | 2025 Analysis of China' s Domestic Storage Market | Optical Communication Chips | China-Domestic Supply Chain | Semiconductor Manufacturing Equipment | - |
| July Ad Booking Deadline: 20-May-2026 Ad Materials Deadline: 29-May-2026 | • | • | Breakthrough Adoption of China-Domestic SiC in Evs | Brain-Computer Interface / Smart Healthcare | GaN Devices | Smart Warehouse | - | - |
| August Ad Booking Deadline: 19-Jun-2026 Ad Materials Deadline: 30-Jun-2026 | • | • | Dawn of Industrial-Scale Humanoid Robotics Production | Industrial Electronics Market | Micro-Motor | Authorized Technology Distribution | Semiconductor Packaging | - |
| September Ad Booking Deadline: 20-Jul-2026 Ad Materials Deadline: 30-Jul-2026 | • | • | Smart Homes Evolving into Proactive Intelligence | Smart Wearables | RISC-V | Low-Volume Electronics Distribution | - | - |
| October Ad Booking Deadline: 20-Aug-2026 Ad Materials Deadline: 28-Aug-2026 | • | • | AI glasses spark the next boom in tech supply chains | Display industry trends | ASIC | Electronic Component Distributor M&A | Advanced Material Application | - |
| November Ad Booking Deadline: 21-Sep-2026 Ad Materials Deadline: 25-Sep-2026 | • | • | GPU/ AI Chips: 10K-GPU Intelligent Computing Cluster Deployment | Data Center | CMOS Image Sensor | AI-Enabled Electronic Component Distribution | - | - |
| December Ad Booking Deadline: 20-Oct-2026 Ad Materials Deadline: 30-Oct-2026 | • | • | Package Leap: Advanced Packaging Redefining Semiconductor Frontiers | Wafer Foundry Trends | RF Front-End | Inventory Management | Wafer Manufacturing | Distributors and supply chain special issue |

Editorial Inquiries

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Note: The publisher retains the right to reschedule any topic in the calendar.